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## BIB DATA SHEET

CONFIRMATION NO. 1783

<b>SERIAL NUMBER</b> 10/801,475	<b>FILING or 371(c) DATE</b> 03/16/2004 <b>RULE</b>	<b>CLASS</b> 438	<b>GROUP ART UNIT</b> 2822	<b>ATTORNEY DOCKET NO.</b> 24061.193 (TSMC2003.1410)		
<b>APPLICANTS</b> Hsien-Wei Chen, Xinying City, TAIWAN; Jiun-Lin Yeh, Taipei City, TAIWAN; Shin-Puu Jeng, Hsinchu, TAIWAN; Yi-Lung Cheng, Danshuei Township, TAIWAN; <b>** CONTINUING DATA *****</b> <b>** FOREIGN APPLICATIONS *****</b> <b>** IF REQUIRED, FOREIGN FILING LICENSE GRANTED **</b> 06/01/2004						
Foreign Priority claimed <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No 35 USC 119(a-d) conditions met <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No Verified and Acknowledged <i>[Signature]</i> Examiner's Signature		<input type="checkbox"/> Met after Allowance <i>[Initials]</i> Initials	<b>STATE OR COUNTRY</b> TAIWAN	<b>SHEETS DRAWINGS</b> 7	<b>TOTAL CLAIMS</b> 20	<b>INDEPENDENT CLAIMS</b> 3
<b>ADDRESS</b> HAYNES AND BOONE, LLP 901 Main Street Suite 3100 Dallas, TX 75202 UNITED STATES						
<b>TITLE</b> System and method of heat dissipation in semiconductor devices						
<b>FILING FEE RECEIVED</b> 900	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:			<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit		